

Customer No.: 31561
Application No.: 10/604,409
Docket NO.:10672-US-PA

REMARKS

Present Status of the Application

This is a full and timely response to the outstanding non-final Office Action mailed on September 21, 2004. Claims 1-19 remain pending of which claims 1, 7 and 12 have been amended and claims 3, 8 and 13 have been cancelled to more accurately describe the invention and to correct informalities. It is believed that no new matter is added by way of these amendments made to the claims or otherwise to the application.

After carefully considering the remarks set forth in this Office Action and the cited references, it is however strongly believed that the cited references are deficient to adequately teach the claimed features as recited in the presently pending claims. The reasons that motivate the above position of the Applicant are discussed in detail hereafter, upon which reconsideration of the claims is most earnestly solicited.

Discussion of Office Action Rejections

The Office Action rejected claim 1-2, 4 and 6-19 under 35 U.S.C. § 103(a), as being unpatentable over the AAPA Fig.1 and in view of Chen et al. (US 2002/0096754, Chen hereinafter).

The present invention is in general related to a stack chip package structure with a thicker adhesive layer around the edges than the central area of a die. Particularly, a

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plurality of surfaces is formed at the edges of the bonding surface surrounding the central surface, wherein the peripheral surfaces are multi-step ladder, curved or sloped surfaces.

Chen, on the other hand, simply teaches forming two recesses 51 at two sides of the lower surface of the upper integrated circuit so that ends of the wirings 44 can be disposed within the recess 51 and are free from being pressed and damaged by the upper integrated circuit 46. There is no suggestion in Chen at all that a peripheral surface of the bonding surface being a multi-step ladder, curved or sloped surface can serve to buffer the stress concentration level at the bottom peripheral sections of the stack structure. The recess in Chen is used for totally difference purpose from that of the present invention. As a matter of fact, the problems solved by the invention were not recognized by Chen, let alone the fact the Chen fails to teach the peripheral surfaces of the bonding surface are multi-ladder, sloped or curved surfaces.

For at least these reasons, Applicants respectfully assert that AAPA in view of Chen fails to render claims 1, 7 and 12 obvious. Since claims 4-6, 9-11 and 14-19 are dependent claims which further define the invention recited in claims 1, 7 and 12, respectively, Applicants respectfully assert that these claims also are in condition for allowance. Thus, reconsideration and withdrawal of this rejection are respectfully requested.

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The Office Action rejected claim 5 under 35 U.S.C. § 103(a), as being unpatentable over the AAPA Fig.1 and in view of Chen et al. (US 2002/0096754) and further in vie of Nakaoka et al. (US 2003/0127722, Nakaoka hereinafter).

With regard to dependent claim 5, Applicant respectfully submits that this claim patently define over the prior art for at least the same reasons as independent claim 1, discussed above. Withdrawal of the rejection is respectfully requested.

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CONCLUSION

For at least the foregoing reasons, it is believed that the presently pending claims 1, 4-7, 9-12, 14-19 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,

Date :

Dec. 20, 2004

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